

Serial No.:	09/870,531	Art Unit:	2827
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REMARKS

The claims have been amended in view of the Office action and in view of the remarks which follow, they are believed to be in condition for allowance. There is a new generic claim 29 which has been added in view of the requirement for restriction. The other claims in the application have been divided into Group I and Group II.

Group I includes claims 1-13, 25-26 and 30.

Group II includes claims 14-16, 27-28 and 31.

The Office Action stated as follows:

"This application contains claims directed to the following patentably distinct species of the claimed invention: the species of forming via holes prior to forming an interconnection, and the species of forming via holes after forming an interconnection."

"Applicant is required under 35 U.S.C. 121 to elect a single disclosed species for prosecution on the merits to which the claims shall be restricted if no generic claim is finally held to be allowable. Currently, there are no claims generic."

The species referred to hereinafter as Group I including claims 1-13, 25-26 and 30 is hereby elected provisionally with traverse since the new generic claim 29 has been added.

The Office Action stated further as follows:

"Applicant is advised that a reply to this requirement must include an identification of the species that is elected consonant with this requirement, and a listing of all claims readable thereon, including any claims subsequently added. An argument that a claim is allowable or that all claims are generic is considered nonresponsive unless accompanied by an election."

Group I includes the wafer upon which an interconnection structure is formed by the steps as follows:

- (A) Provide the wafer;
- (B) Form the interconnection structure;
- (C) Cover the interconnection structure with a protective overcoat;
- (D) Form a temporary bond between the interconnection structure and the wafer;
- (E) Thin the wafer;
- (F) Form via holes;
- (G) Form metallization in the via holes;
- (H) Remove the temporary bond.

Serial No.:	09/870,531	Art Unit:	2827
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Group II includes the wafer upon which an interconnection structure is formed by the steps as follows:

- (A) Provide the wafer;
- (F) Form via holes;
- (I) Form dielectric layer;
- (G) Form metallization in the via holes;
- (B) Form the interconnection structure;
- (C) Cover the interconnection structure with a protective overcoat;
- (D) Form a temporary bond between the protective overcoat and a wafer holder;
- (E) Thin the wafer;
- (J) Remove distal dielectric;
- (H) Remove the temporary bond.

Group I also includes the wafer upon which an interconnection structure is formed by the steps as follows:

- (A) Provide the wafer;
- (B) Form the interconnection structure;
- (C) Cover the interconnection structure with a protective overcoat;
- (D) Form a temporary bond between the protective overcoat and a wafer holder;
- (E) Thin the wafer;
- (F) Form via holes;
- (G) Form metallization in the via holes;
- (H) Remove the temporary bond.

Serial No.:	09/870,531	Art Unit:	2827
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Group II also includes the wafer upon which an interconnection structure is formed by the steps as follows:

- (A) Provide the wafer;
- (F) Form via holes;
- (I) Form dielectric layer;
- (G) Form metallization in the via holes;
- (B) Form the interconnection structure;
- (C) Cover the interconnection structure with a protective overcoat;
- (D) form a temporary bond between the protective overcoat and a wafer holder;
- (E) Thin the wafer;
- (J) Remove distal dielectric;
- (H) Remove the temporary bond.

Generic claim 29 includes the steps defined broadly as follows:

- (A) First start with the silicon wafer as the base for the SBP;
- Then perform alternative sequences of the steps which follow:
- (D) Form a temporary bond of a wafer holder to the first side of the wafer;
 - (E) Thin the reverse side of the wafer;
 - (F) Form via holes through the wafer;
 - (G) Form metallization in the via holes;
 - (H) Remove the temporary bond.

The heart of the invention as it is defined in generic claim 29 is that the wafer in the various configurations claimed is bonded to the wafer holder prior to thinning and that the wafer holder is removed after the via holes have been formed and filled with metallization which extends through the thinned wafer.

The Office Action stated further as follows:

"Upon the allowance of a generic claim, applicant will be entitled to consideration of claims to additional species which are written in dependent form or otherwise include all the limitations of an allowed generic claim as provided by 37 CFR 1.141. If claims are added after the election, applicant must indicate which are readable upon the elected species. MPEP § 809.02(a)."

Serial No.:	09/870,531	Art Unit:	2827
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It is believed that the new claims have been so identified above thereby satisfying the requirement of MPEP § 809.02(a).

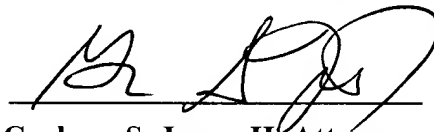
The Office Action stated further as follows:

"Should applicant traverse on the ground that the species are not patentably distinct, applicant should submit evidence or identify such evidence now of record showing the species to be obvious variants or clearly admit on the record that this is the case. In either instance, if the examiner finds one of the inventions unpatentable over the prior art, the evidence or admission may be used in a rejection under 35 U.S.C. 103(a) of the other invention."

At this time, Applicants are not traversing on the ground that "the species are not patentably distinct" and it is believed that no admission is being made which would be applicable under 35 U.S.C. 103(a) and no such admission is intended. Moreover, because the generic claim is believed to be patentable, it is believed that the requirement for restriction is now moot.

In view of the amendments and the above remarks favorable action including allowance of the claims and the application as a whole are respectfully solicited.

Respectfully submitted,



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